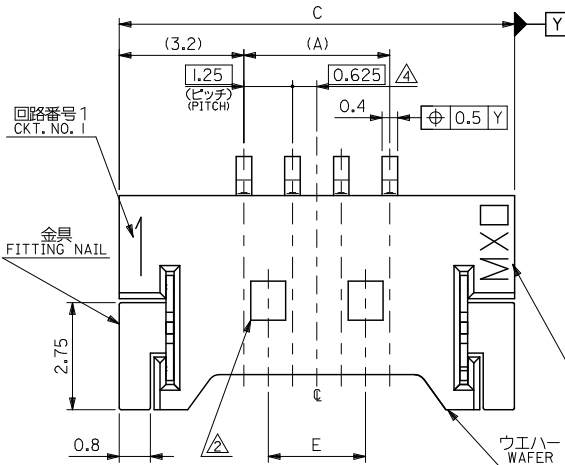


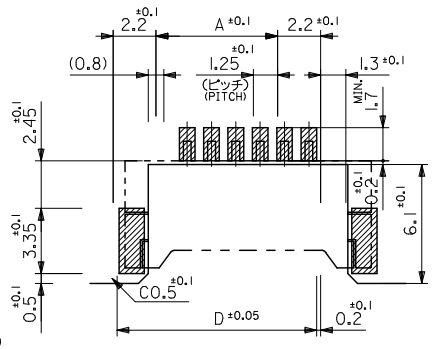
10 9 8 7 6 5 4 3 2 1



**注記 NOTES**

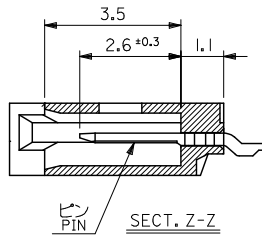
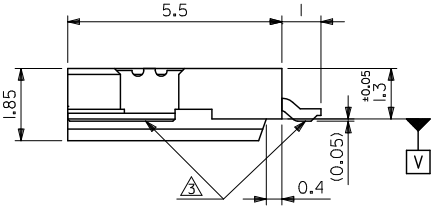
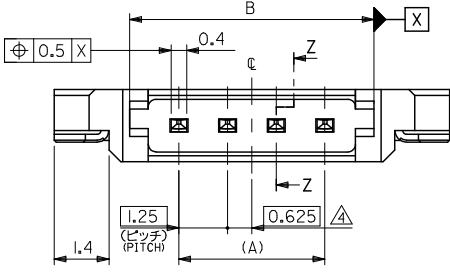
1. 嵌合相手: 51146 シリーズ  
MATES WITH: 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面[V]からのソルダータールと金具の半田付け面のズレ量は、上方向に0.05MAX、下方向0.15MAX、とし、相互のバラツキ量は0.1MAXとする。  
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]: UPPER DIRECTION 0.05MAX, LOWER DIRECTION 0.15MAX, OFFSET BETWEEN UPPER AND LOWER 0.1MAX.
4. 偶数極の製品に適用。  
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL  
ウエハー WAFER: PPHS, UL94V-0  
ピン: リン青銅 (コンタクト部: 金メッキ, テール部: 半田メッキ)  
PIN: PHOS-BRO (CONTACT: Au PLATING, TAIL: Sn-Pb PLATING)  
金具: リン青銅 (半田メッキ)  
FITTING NAIL: PHOS-BRO (Sn-Pb PLATING)

トレードマーク TRADE MARK



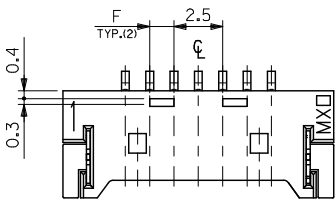
参考基板レイアウト  
RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)

16.25	22.5	40.25	42.65	38.77	36.25	53779-3010	30
15	22.5	37.75	40.15	36.27	33.75		-2810 28
13.75	22.5	35.25	37.65	33.77	31.25		-2610 26
12.5	22.5	32.75	35.15	31.27	28.75		-2410 24
11.25	22.5	30.25	32.65	28.77	26.25		-2210 22
8.75	22.5	27.75	30.15	26.27	23.75		-2010 20
7.5	20	25.25	27.65	23.77	21.25		-1810 18
6.25	17.5	22.75	25.15	21.27	18.75		-1610 16
6.25	16.25	21.5	23.9	20.02	17.5		-1510 15
5	15	20.25	22.65	18.77	16.25		-1410 14
3.75	12.5	17.75	20.15	16.27	13.75		-1210 12
2.5	8.75	14	16.4	12.52	10		-0910 9
1.25	7.5	12.75	15.15	11.27	8.75		-0810 8
--	5	10.25	12.65	8.77	6.25		-0610 6
--	3.75	9	11.4	7.52	5		-0510 5
--	2.5	7.75	10.15	6.27	3.75		-0410 4
--	--	6.5	8.9	5.02	2.5		-0310 3
--	--	5.25	7.65	3.77	1.25	53779-0210	2
F	E	D	C	B	A	MATERIAL NO.	CKT. 極数

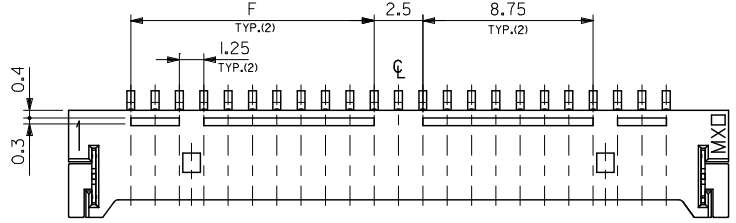


REVISED E.C. NO: J2008-4402 DRAWN: ANAKURAA 2008/07/01 CHECKED: HARUYAMA 2008/07/01 APPROVED: ITO 2008/11/18 H REVISION DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY S. MATSUZAKI	DATE '01/05/11	TITLE 1.25 WIRE TO BOARD CONN. WAFER ASSY FOR SMT. (SHEET 1 OF 2)		
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '01/05/11			
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '01/05/11	MOLEX INCORPORATED DOCUMENT NO. SD-53779-003 SHEET NO. 1 OF 2		
ANGULAR ±3°		MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

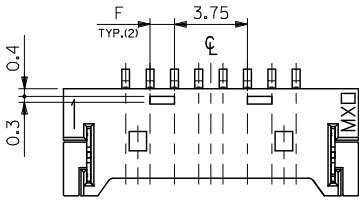
10 9 8 7 6 5 4 3 2 1



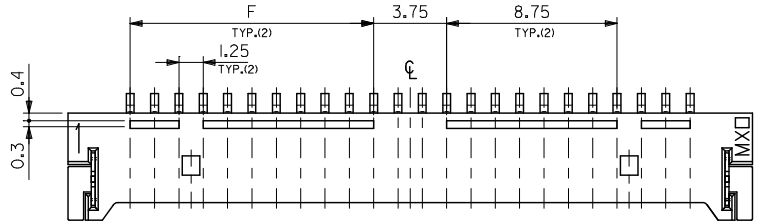
7~19極の奇数極に適用  
APPLY FOR ODD CIRCUITS OF 7~19



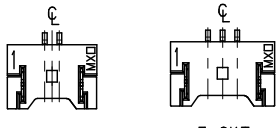
21極以上の奇数極に適用  
APPLY FOR ODD CIRCUITS 21~29



8~20極の偶数極に適用  
APPLY FOR EVEN CIRCUITS OF 8~20



22極以上の偶数極に適用  
APPLY FOR EVEN CIRCUITS 22~30



ロック形状図  
LOCK CONFIGURATION

REVISED EC NO: J2008-4402 DRAWN: KAKURAA 2008/07/01 CHKD: HARUYAMA 2008/07/01 APPR: NIKITA 2008/11/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY S. MAYSUZAKI	DATE '01/05/11	TITLE 1.25 WIRE TO BOARD CONN. WAFFER ASS FOR S.M.T. (SHEET 2 OF 2)	
	10 OVER 30 UNDER	±0.25	CHECKED BY T. YAMAGUCHI	DATE '01/05/11		
	30 OVER	±0.3	APPROVED BY T. YAMAGUCHI	DATE '01/05/11	MOLEX INCORPORATED	
DESCRIPTION ANGULAR ±3°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-53779-003	SHEET NO. 2 OF 2	